

SPECIFICATIONS CLF30R3C

OUTLINES DIMENSIONS

Description

- *Round Type
- *T1 (3mm) Diameter
- *Lens Color: Water Clear
- *Without Flange

Features

- *Emitted Color: Red
- *High Luminous Intensity
- *Technology: InGaAIP
- *Viewing Angle: 44°

1.5MAX 25.0MIN 25.0MIN 1.0MIN

Notes:

- 1. All Dimensions are in millimeters (inches).
- 2. Tolerance is \pm 0.25mm (0.01") unless otherwise noted.
- 3. Specifications are subject to change without notice.

Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle
CLF30R3C	InGaAlP	Red	Water Clear	44°



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ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit
Power Dissipation	Po	75	mW
Pulse Current Forward Current	IFP	90	mA
Continuous Forward Current	lF	30	mA
Reverse Voltage	VR	5	V
Operating Temperature Range	Topr	-40~+85	°C
Storage Temperature Range	Тѕтс	-40~+100	°C
I _{FP} = Pulse Width ≤ 10 ms, Duty Ratio ≤1/10. Soldering Condition: 260 °C/ 5s			

OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

Darameter	Symbol	Test Condition	Value			Lloit
Parameter			Min	Тур	Max	Unit
Luminous Intensity	lv	I _F = 20mA	700	1500	ı	mcd
Forward Voltage	VF	I _F = 20mA	1	2.1	2.4	V
Reverse Leakage Current	lr	V _R = 5V	1	-	10	μΑ
Viewing Angle	201/2	I _F = 20mA	1	44	1	deg
Dominant Wavelength	λ D	I⊧ = 20mA	-	630	-	nm
Spectral Line half-width	Δλ	I⊧ = 20mA	-	20	-	nm

^{*}Tolerance of viewing angle: -10 / +5 deg.



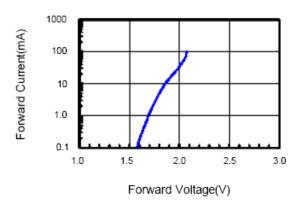
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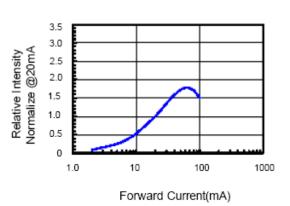


OPTICAL CHARACTERISTIC CURVES

Forward Current vs. Forward Voltage

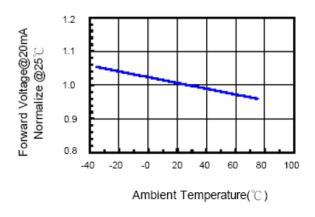
Relative Intensity vs. Forward Current

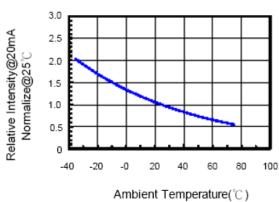




Forward Current vs. Ambient Temperature

Relative Intensity vs. Wavelength





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SOLDERING CONDITIONS – LAMP TYPE LED

- * Solder the LED no closer than 3mm from the base of the epoxy bulb. Soldering beyond the base of the tie bar is recommended.
- * Recommended soldering conditions

Dip Soldering			
Pre-Heat	100 °C Max		
Pre-Heat Time	60 Second Max		
Solder Bath Temperature	260 °C Max		
Dippng Time	5 Second Max		
Dipping Position	No lower than 3mm from the base of the epoxy		

Hand Soldering				
	3mm Series	Others		
Tomporature Soldering Time	300 °C Max	350 °C Max		
Temperature Soldering Time Position	3 Second Max	3 Second Max		
	No closer than 3mm from the	No closer than 3mm from the		
	base of the epoxy	base of the epoxy		

- * Do not apply any stress to the lead. Particularly when heated.
- * The LED must not be repositioned after soldering.
- * After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- * Direct soldering onto a PC board should be avoided. Mechanical stress to the resin may be caused by the PC board warping or from the clinching and cutting of the leadframes. When it is absolutely necessary, the LEDs may be mounted in this fashion, but, the user will assume responsibility for any problems. Direct soldering should only be done after testing has confirmed that no damage, such as wire bond failure or resin deterioration, will occur. LEDs should not be soldered directly to double sided PC boards because the heat will deteriorate the epoxy resin.
- * When it is necessary to clamp the LEDs to prevent soldering failure, it is important to minimize the mechanical stress on the LEDs.
- * Cut the LED leadframes at room temperature. Cutting the leadframes at high temperature may cause LED failure.

